CLAIMS

1. A tape for semiconductor processing, comprising a temporary adhesive tape having a substrate film; and a temporary adhesive layer formed on at least one surface side of the substrate film,

wherein regarding the temporary adhesive tape, the sum of the average value of the differential value of the thermal deformation rate in the MD direction per 1°C between 40°C and 80°C measured at the time of raising temperature by means of a thermomechanical characteristics testing machine, and the average value of the differential value of the thermal deformation rate in the TD direction per 1°C between 40°C and 80°C measured at the time of raising temperature by means of a thermomechanical characteristics testing machine, is a negative value, and

the tape for semiconductor processing is used for semiconductor processing including an expansion process of expanding the temporary adhesive tape.

2. A tape for semiconductor processing, comprising a temporary adhesive tape having a substrate film; and a temporary adhesive layer formed on at least one surface side of the substrate film,

wherein the substrate film is formed from an ionomer resin or a mixed resin composition of polypropylene and styrene-butadiene copolymer, and

regarding the temporary adhesive tape, the sum of the average value of the differential value of the thermal

deformation rate in the MD direction per 1°C between 40°C and 80°C measured at the time of raising temperature by means of a thermomechanical characteristics testing machine, and the average value of the differential value of the thermal deformation rate in the TD direction per 1°C between 40°C and 80°C measured at the time of raising temperature by means of a thermomechanical characteristics testing machine, is a negative value.

3. The tape for semiconductor processing according to claim 1 or 2, wherein an adhesive layer is laminated on the temporary adhesive layer side.

4. The tape for semiconductor processing according to any one of claims 1 to 3, wherein the tape for semiconductor processing is used for full-cut and half-cut blade dicing, laser dicing, or stealth dicing using a laser.